PL138-58

2.5V-3.3V Low-Skew 1-4 PECL Fanout Buffer

FEATURES

- Four differential 2.5V/3.3V LVPECL output pairs.
- Output Frequency: ≤ 266 MHz.
- Selectable CLK0 or CLK1 inputs for redundant and multiple frequency fanout applications
- Translates single-ended LVCMOS or LVTTL input to 3.3V or 2.5V LVPECL differential outputs.
- Output Skew: 25ps (typ).
- Part-to-part skew: 85ps (typ).
- Propagation delay: 0.7ns (typ).
- Additive Jitter: 50 fs (typ).
- Operating Supply Voltage: 2.375V ~ 3.63V.
- Operating temperature range from -40°C to 85°C.
- Package availability: 16-pin QFN and 20-pin TSSOP

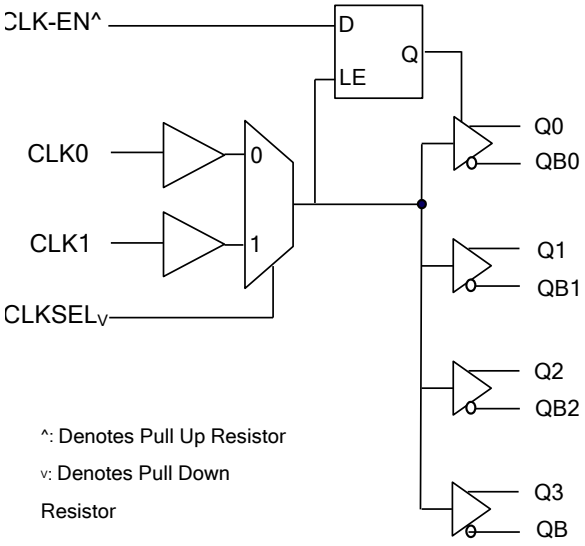
DESCRIPTION

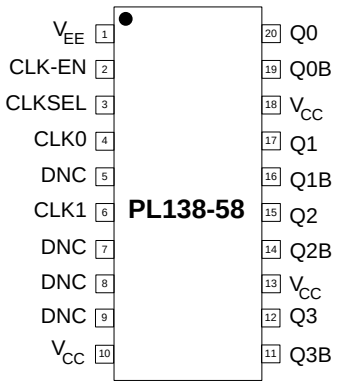
The PL138-58 is a high performance low-cost 1**:** 4 outputs Differential LVPECL fanout buffer, with very low-skew and LVCMOS/LVTTL input interface for 3.3V and 2.5V operations.

PL138-58's two single-ended clock inputs are designed to accept a standard LVCMOS or LVTTL signal levels and produce a high quality set of 2.5V or 3.3V LVPECL outputs with the lowest possible skew, guaranteed for part-to-part or lot-to lot. The clock enable is internally synchronized to assure no runt clock pulses on the output during asynchronous assertion/deassertion of the clock enable pin.

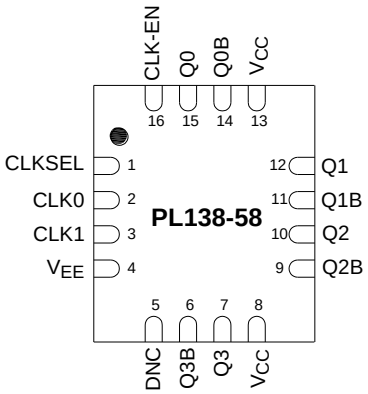
Designed to fit in a small form-factor package, PL138 family offers very low-power consumption, and the lowest additive jitter of any comparable device.

BLOCK DIAGRAM





20-Pin TSSOP Package



16-Pin QFN Package

PIN DESCRIPTIONS

Name	Package Pin #		Type	Description
	QFN-16	TSSOP-20		
Vcc	8, 13	10, 13, 18	P	Power Supply pin connection
QB0 ~ QB3	6, 9, 11, 14	11, 14, 16, 19	O	LVPECL Complementary output
Q0 ~ Q3	7, 10, 12, 15	12, 15, 17, 20	O	LVPECL True output
V_{EE}	4	1	P	Power Supply pin connection
CLK-EN	16	2	I	Synchronizing clock enable. When HIGH, clock outputs follow clock input. When LOW, Q outputs are forced low, QB outputs are forced high. LVCMOS / LVTTL interface levels. 50kΩ Internal Pull-Up Resistor.
CLK-SEL	1	3	I	Clock select input. When HIGH, selects CLK1 input. When LOW, selects CLK0 input. LVCMOS / LVTTL interface levels. 50kΩ Internal Pull-Down Resistor.
CLK0	2	4	I	LVCMOS, LVTTL Clock input.
DNC	5	5, 7, 8, 9	-	Do Not Connect.
CLK1	3	6	I	LVCMOS, LVTTL Clock input.

INPUT CLOCK CONTROL FUNCTION

Inputs			Outputs	
CLK-EN	CLKSEL	Source	Q0:Q3	Q0B:Q3B
0	0	CLK0	Disabled Low	Disabled High
0	1	CLK1	Disabled Low	Disabled High
1	0	CLK0	Enabled	Enabled
1	1	CLK1	Enabled	Enabled

ELECTRICAL SPECIFICATIONS

Absolute Maximum Ratings

PARAMETERS	SYMBOL	MIN.	MAX.	UNITS
Supply Voltage	V_{DD}		4.6	V
Input Voltage, dc	V_I	-0.5	V_{DD}+0.5	V
Output Voltage, dc	V_O	-0.5	V_{DD}+0.5	V
Storage Temperature	T_S	-65	150	°C
Ambient Operating Temperature*	T_A	-40	85	°C
Junction Temperature	T_J		110	°C
Lead Temperature (soldering, 10s)			260	°C
ESD Protection, Human Body Model	2			kV

Exposure of the device under conditions beyond the limits specified by Maximum Ratings for extended periods may cause permanent damage to the device and affect product reliability. These conditions represent a stress rating only, and functional operations of the device at these or any other conditions above the operational limits noted in this specification is not implied.

* **Note**: Operating Temperature is guaranteed by design for all parts (COMMERCIAL and INDUSTRIAL), but tested for COMMERCIAL grade only.

DC CHARACTERISTICS, VCC = 3.3V ±10%; VEE = 0V; T_A= -40ºC TO +85ºC

PARAMETER	SYMBOL	-40°C			25°C			80°C			UNITS
		MIN	TYP	MAX	MIN	TYP	MAX	MIN	TYP	MAX	
Output High Voltage*	VOH	2.215	2.320	2.420	2.275	2.350	2.420	2.275	2.35	2.420	V
Output Low Voltage*	VOL	1.470	1.610	1.745	1.490	1.585	1.680	1.490	1.585	1.680	V
Input High Voltage†	VIH	$0.7V_{CC}$		V_{CC}+0.3	$0.7V_{CC}$		V_{CC}+0.3	$0.7V_{CC}$		V_{CC}+0.3	V
Input Low Voltage†	VIL	-0.3		$0.3V_{CC}$	-0.3		$0.3V_{CC}$	-0.3		$0.3V_{CC}$	V
Input High Current	I_{IH}			200			200			200	µA
Input Low Current	I_{IL}	-150			-150			-150			µA

DC CHARACTERISTICS, VCC = 2.5V ±5%; VEE = 0V; T_A= -40ºC TO +85ºC

PARAMETER	SYMBOL	-40°C			25°C			80°C			UNITS
		MIN	TYP	MAX	MIN	TYP	MAX	MIN	TYP	MAX	
Output High Voltage*	VOH	1.415	1.520	1.620	1.475	1.550	1.620	1.475	1.55	1.620	V
Output Low Voltage*	VOL	0.670	0.810	0.945	0.690	0.785	0.880	0.690	0.785	0.880	V
Input High Voltage†	VIH	$0.7V_{CC}$		V_{CC}+0.3	$0.7V_{CC}$		V_{CC}+0.3	$0.7V_{CC}$		V_{CC}+0.3	V
Input Low Voltage†	VIL	-0.3		$0.3V_{CC}$	-0.3		$0.3V_{CC}$	-0.3		$0.3V_{CC}$	V
Input High Current	I_{IH}			150			150			150	µA
Input Low Current	I_{IL}	-120			-120			-120			µA

Input and output parameters vary 1:1 with VCC. VEE can vary +0.925V to -0.5V.

Input parameters vary with the ratio of VI : (VCC - VEE)

* Outputs terminated with 50Ω to VCCO – 2V.

† VIH/VIL apply to CLK0, CLK1, CLKEN, CLKSEL.

AC Electrical Characteristics

V_{CC} = -3.8V to -2.375V or, V_{CC} = 2.375V to 3.8V; V_{EE} = 0V, T_A = -40°C to 85°C

PARAMETER		SYMBOL	-40°C			25°C			80°C			UNITS
			MIN	TYP	MAX	MIN	TYP	MAX	MIN	TYP	MAX	
Output Frequency		f_{MAX}			266			266			266	MHz
Propagation Delay*		t_{PD}	570	700	800	610	740	840	650	810	940	ps
Output Skew ** †		tsk(o)		25	37		25	37		25	37	ps
Part-to-Part Skew *** †		tsk(pp)		85	225		85	225		85	225	ps
Buffer Additive Phase Jitter, RMS; refer to Additive Phase Jitter Section		t_{APJ}			100			100			100	fs
Output Rise/Fall Time	20% to 80%	t_R / t_F			300			300			300	ps

All parameters are measured at f ≤ 266MHz, unless otherwise noted.

* Measured from the differential input crossing point to the differential output crossing point.

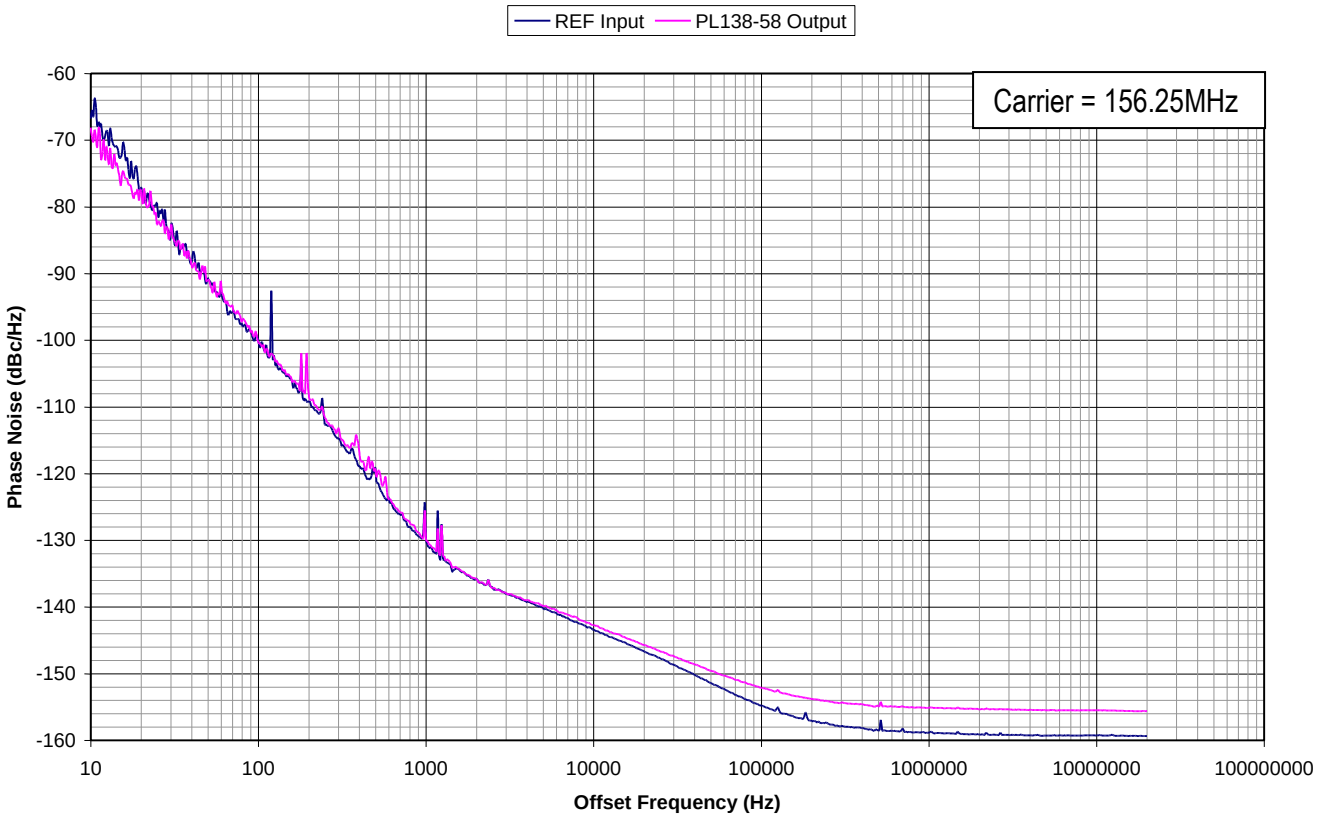
** Defined as skew between outputs at the same supply voltage and with equal load conditions. Measured at the output differential cross points.

*** Defined as skew between outputs on different devices operating at the same supply voltages and with equal load conditions. Using the same type of inputs on each device, the outputs are measured at the differential cross points.

†This parameter is defined in accordance with JEDEC Standard 65.

NOISE CHARACTERISTICS (Commercial and Industrial Temperature Devices)

Parameter	Description	Test Conditions	Min.	Typ.	Max.	Unit
t_{APJ}	Additive Phase Jitter	V_{DD}=3.3V, Frequency=156.25MHz Offset=12KHz ~ 20MHz		50	100	fs
		V_{DD}=3.3V, Frequency=25MHz Offset=1KHz ~ 1MHz		50	100	fs

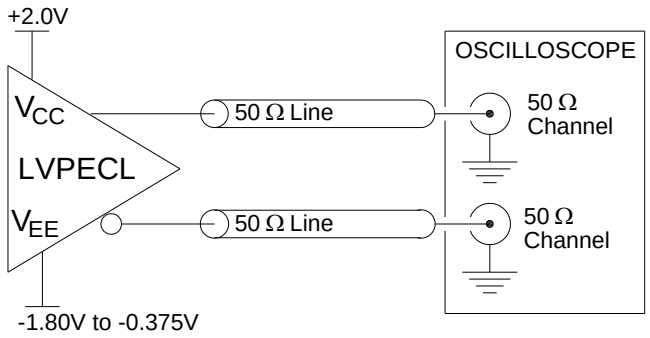


When a buffer is used to pass a signal then the buffer will add a little bit of its own noise. The phase noise on the output of the buffer will be a little bit more than the phase noise in the input signal. To quantify the noise addition in the buffer we compare the Phase Jitter numbers from the input and the output. The difference is called "Additive Phase Jitter". The formula for the Additive Phase Jitter is as follows:

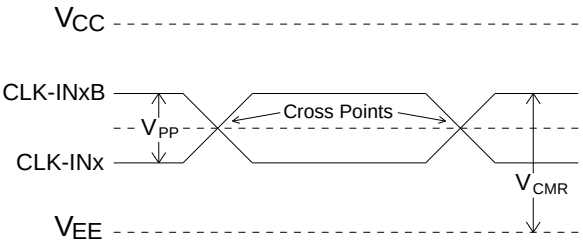
$$\text{Additive Phase Jitter} = \sqrt{(\text{Output Phase Jitter})^2 - (\text{Input Phase Jitter})^2}$$

PARAMETER MEASUREMENT INFORMATION

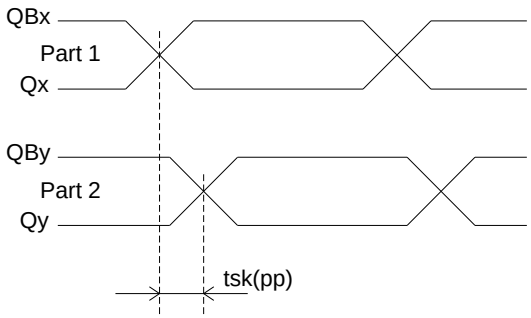
Output Waveform Test Circuit:



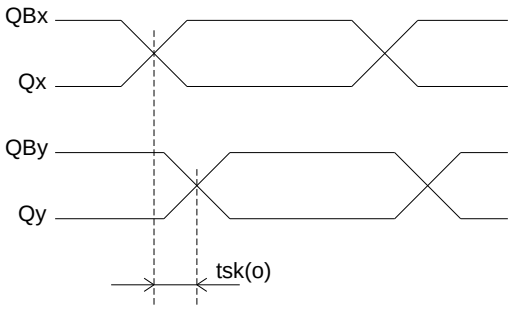
Differential Input Level:



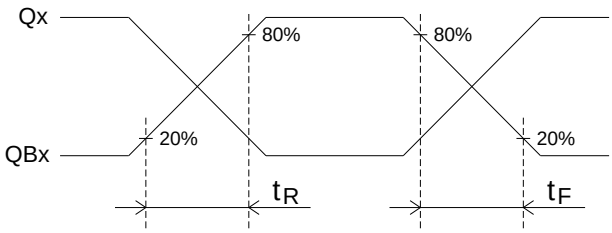
Part-to-Part Skew:



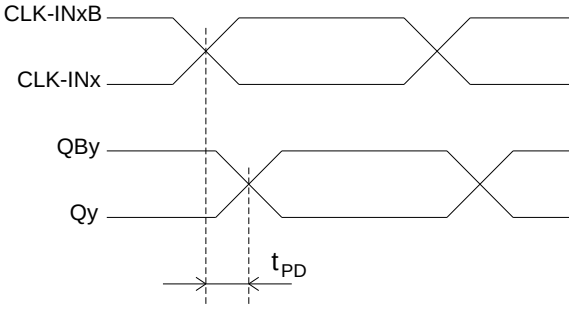
Output Skew:



Output Rise/Fall Time:



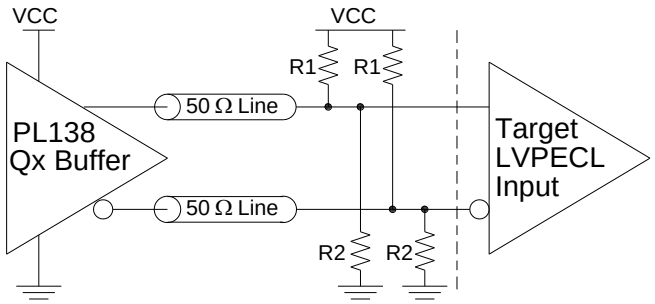
Propagation Delay:



TERMINATION FOR LVPECL OUTPUTS

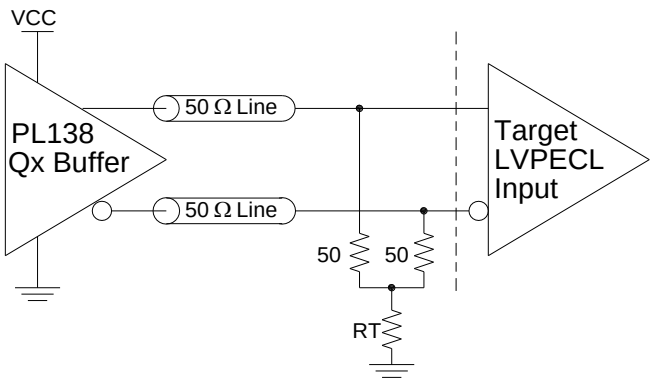
The required termination for LVPECL is 50Ω to a V_{CC}-2V DC voltage level. Below are two schematics to implement this termination.

LVPECL Termination Schematic #1:



VCC=3.3V, Ideal values: R1=127Ω , R2=82.5Ω
Commercial values (E24): R1=130Ω , R2=82Ω
VCC=2.5V, Ideal values: R1=250Ω , R2=62.5Ω
Commercial values (E24): R1=240Ω , R2=62Ω

LVPECL Termination Schematic #2:



Schematic #2 is an alternative simplified termination.
VCC=3.3V, Ideal value: RT=48.7Ω
Commercial value: RT=50Ω (E24: 51Ω)
VCC=2.5V, Ideal value: RT=18.7Ω
Commercial value: RT=18Ω

POWER CONSIDERATIONS

Driving LVPECL outputs requires an amount of power that can warm up the chip significantly.

The general requirement for the chip is that the junction temperature should not exceed +110°C.

The power consumption can be divided into two parts:

1) Core power dissipation
2) Output buffers power dissipation

CORE POWER DISSIPATION

The chip core power is equal to VCC×IEE. With a worst case VCC and IEE the power dissipation in the core is 3.63V×65mA=236mW.

OUTPUT BUFFER POWER DISSIPATION

The output buffers are not exposed to the full VCC-VEE voltage. On the differential output, one line is at logic 1 with a small voltage across the buffer and a large output current. The other line is at logic 0 with a larger voltage across the buffer and a smaller output current. The power dissipation per output buffer is 32mW. Only buffers that are loaded will have power dissipation. With all 4 buffers loaded the worst case output buffer power dissipation will be 128mW.

Total Chip Power Dissipation, worst case, is 236mW + 128mW = 364mW.

JUNCTION TEMPERATURE

How much the chip is warmed up from the power dissipation depends upon the thermal resistance from the chip to the environment, also known as “junction to ambient”. The thermal resistance depends upon the type of package, how the package is assembled to the PCB and if there is additional air flow for improved cooling. For the LQFP package with use of the Thermal Relief pad, the thermal resistance is as follows:

TSSOP 20-pin Package	Air Flow Velocity in Linear Feet per Minute		
	0	200	500
JEDEC Standard Multi Layer PCB	θ_{JA} = 73°C/W	θ_{JA} = 67°C/W	θ_{JA} = 64°C/W

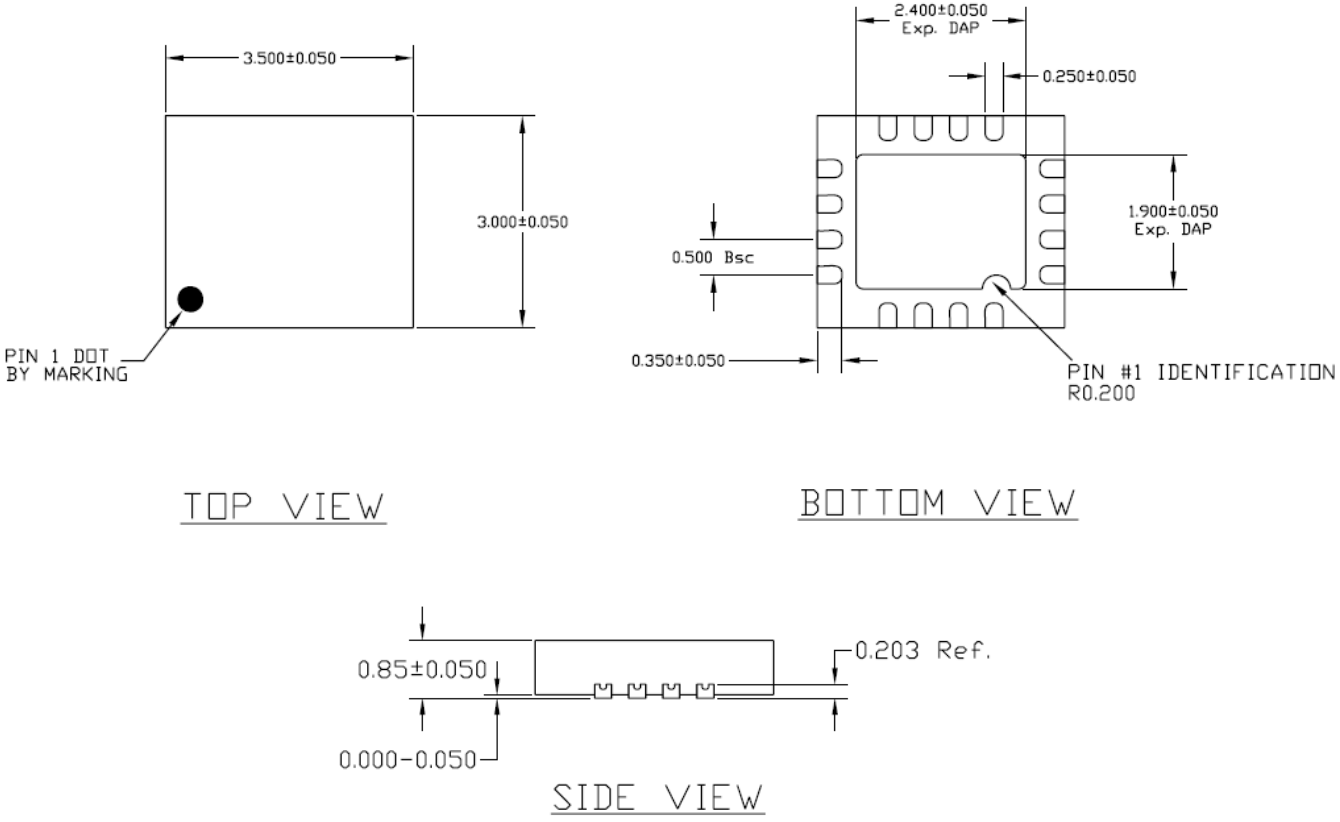
The temperature of the chip (junction) will be higher than the environment (ambient) with an amount equal to θ_{JA} × Power. For an ambient temperature of +70°C, all outputs loaded and no air flow, the junction temperature T_J = 70°C+73×0.364 = 97°C.

QFN 16-pin Package	Air Flow Velocity in Linear Feet per Minute		
	0	200	500
JEDEC Standard Multi Layer PCB	θ_{JA} = 60°C/W	θ_{JA} = 53°C/W	θ_{JA} = 46°C/W

The temperature of the chip (junction) will be higher than the environment (ambient) with an amount equal to θ_{JA} × Power. For an ambient temperature of +85°C, all outputs loaded and no air flow, the junction temperature T_J = 85°C+60×0.364 = 107°C.

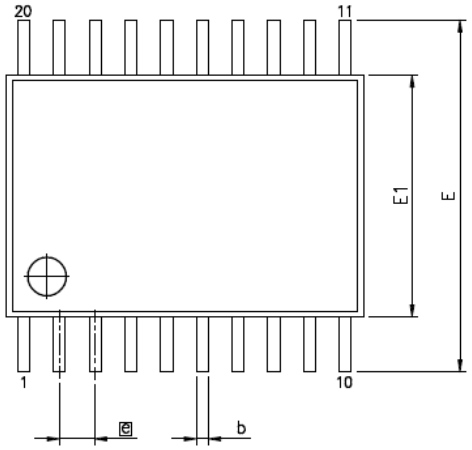
PACKAGE DRAWING (GREEN PACKAGE COMPLIANT)

QFN 16L 3.0 X 3.5 mm

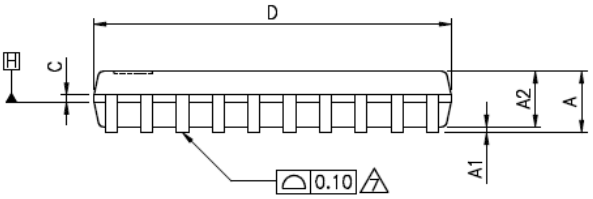


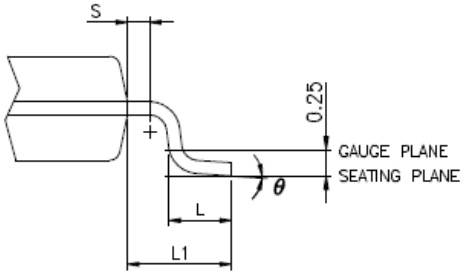
NOTE:
1. ALL DIMENSIONS ARE IN MILLIMETERS.
2. MAX. PACKAGE WARPAGE IS 0.05 mm.
3. MAXIMUM ALLOWABE BURRS IS 0.076 mm IN ALL DIRECTIONS.
4. PIN #1 ID ON TOP WILL BE LASER MARKED.

TSSOP173 20L









VARIATIONS (ALL DIMENSIONS SHOWN IN MM)

SYMBOLS	MIN.	NOM.	MAX.
A	–	–	1.20
A1	0.05	–	0.15
A2	0.80	0.90	1.05
b	0.19	–	0.30
C	0.09	–	0.20
D	6.40	6.50	6.60
E1	4.30	4.40	4.50
E		6.40 BSC	
e		0.65 BSC	
L1		1.00 REF	
L	0.50	0.60	0.75
S	0.20	–	–
θ	0°	–	8°

NOTES:

1. JEDEC OUTLINE :
   STANDARD : MO-153 AC REV.F
   THERMALLY ENHANCED : MO-153 ACT REV.F
2. DIMENSION "D" DOES NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS. MOLD FLASH, PROTRUSIONS OR GATE BURRS SHALL NOT EXCEED 0.15 PER SIDE.
3. DIMENSION "E1" DOES NOT INCLUDE INTERLEAD FLASH OR PROTRUSION. INTERLEAD FLASH OR PROTRUSION SHALL NOT EXCEED 0.25 PER SIDE.
4. DIMENSION "b" DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.08 MM TOTAL IN EXCESS OF THE "b" DIMENSION AT MAXIMUM MATERIAL CONDITION. DAMBAR CANNOT BE LOCATED ON THE LOWER RADIUS OF THE FOOT. MINIMUM SPACE BETWEEN PROTRUSION AND ADJACENT LEAD IS 0.07 MM.
5. DIMENSIONS "D" AND "E1" TO BE DETERMINED AT DATUM PLANE H .

ORDERING INFORMATION (GREEN PACKAGE)

For part ordering, please contact our Sales Department:
2180 Fortune Drive, San Jose, CA 95131, USA
Tel: (408) 944-0800 Fax: (408) 474-1000

PART NUMBER

The order number for this device is a combination of the following:
Part number, Package type and Operating temperature range

PL138-58 X X - R

Part Number

R=Tape and Reel

Package Type
Q=QFN
O=TSSOP

Temperature Range
C= Commercial (0°C to +70°C)
I= Industrial (-40°C to +85°C)

Part/Order Number	Marking	Package Option
PL138-58QC	P138 58 LLLLL	16-Pin QFN
PL138-58QI	P138 58I LLLLL	16-Pin QFN
PL138-58OC	P138-58 OC LLLLL	20-Pin TSSOP (Tube)

***Note: LLLLL designates lot number**

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